



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR DPAK TO-252-4L</b>					
<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
BOND INT	240	120,000	200 °C + N2	0	0.00
HAST	495	49,500	130 °C, 85 % RH	0	0.00
Pressure Pot	660	63,360	121°, 15 PSIG	0	0.00
Solder DUNK	185	555	260 °C, 10 SEC	0	0.00
Solderability	135	1,080	883 M2003	0	0.00
Temp Cycle	550	536,000	- 65 °C - 150 °C	0	0.00